

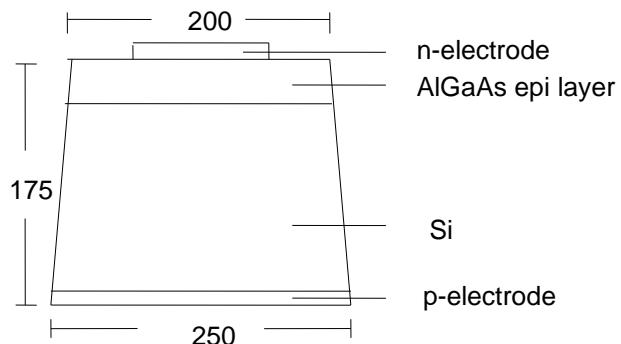
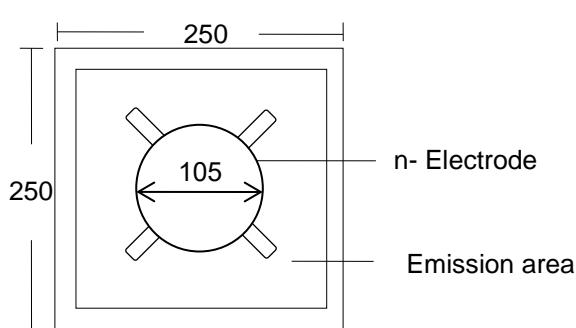
### ■ Features :

- Suitable for New Creative Products

### ■ Typical Applications :

- Home entertainment
- Light source for CMOS & CCD camera
- Security camera, CCTV

### ■ Outline Dimensions : (Unit: um)



### ■ Physical Structure :

Chip dimension	Chip size	250 x 250um
	Thickness	175±25 um
	Emission area	200 um
	Bonding pad	105 um
Electrode	Top: N (cathode)	Gold
	Backside: P (anode)	Gold
Surface condition	Frosted	

\*C2

### ■ Electro-Optical Characteristics : (Ta = 25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward voltage	V <sub>FH</sub>	I <sub>F</sub> = 50mA	1.2	-	1.6	V
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 10V	-	-	1	μA
Radiant Power	P <sub>o</sub>	I <sub>F</sub> = 50 mA	5	-	10	mW
Wavelength	λ <sub>P</sub>	I <sub>F</sub> = 50 mA	940	945	950	nm
Spectral width at half height	△λ	I <sub>F</sub> = 50 mA	-	45	-	nm

## ■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

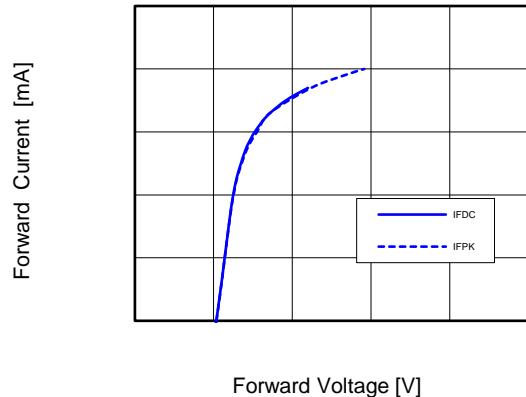


Fig 2. Relative Radiant Power vs. Wavelength

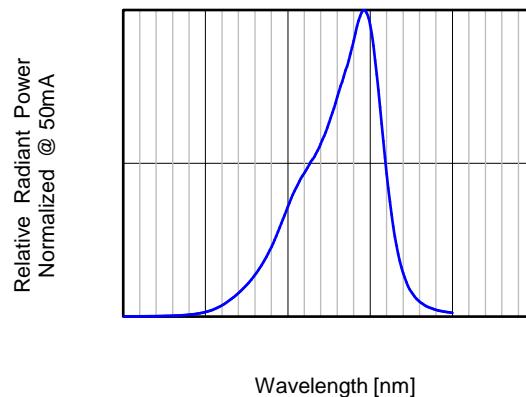
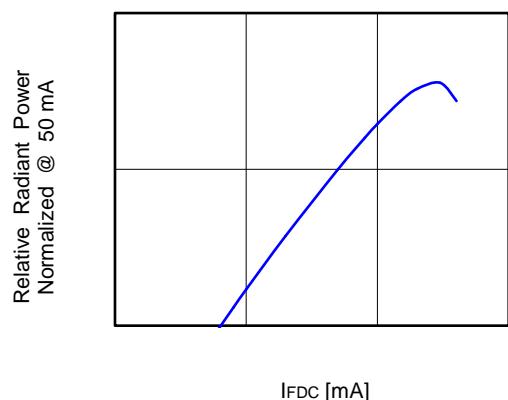
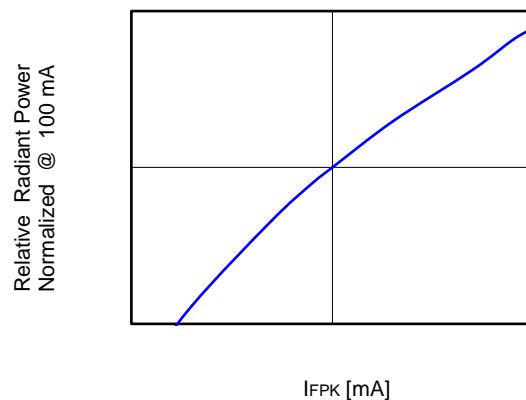
Fig 3. Relative Radiant Power  
vs. Forward DC CurrentFig 4. Relative Radiant Power  
vs. Forward Peak Current

Fig 5. Forward DC Voltage vs. Temperature

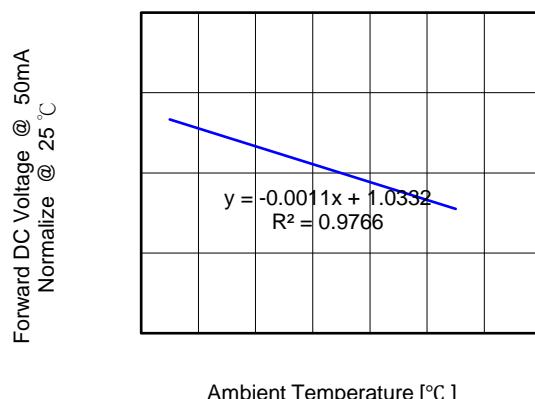


Fig 6. Relative Radiant Power vs. Temperature

